



SURFACE MOUNT ULTRAFAST RECOVERY RECTIFIER

Reverse Voltage - 50 to 1000 V

Forward Current - 1 A

FEATURES

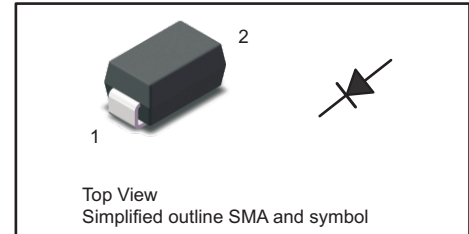
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- High efficiency
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SMA
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.055g / 0.002oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	US1A	US1B	US1D	US1G	US1J	US1K	US1M	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ Fig.1	I _{F(AV)}	1							A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	30							A
Peak Forward Surge Current,1ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	60							A
I ² t Rating for fusing(3ms≤t≤8.3ms)	I ² t	3.7							A ² S
Maximum Instantaneous Forward Voltage at 1 A	V _F	1.0			1.3	1.65			V
Maximum DC Reverse Current at Rated DC Blocking Voltage T _j = 25 °C T _j =125 °C	I _R	5 100							μA
Typical Junction Capacitance ⁽¹⁾	C _j	23			16	13	12		pF
Maximum Reverse Recovery Time ⁽²⁾	t _{rr}	50				75			ns
Typical Thermal Resistance ⁽³⁾	R _{θJA} R _{θJC} R _{θJL}	100 20 25							°C/W
Operating and Storage Temperature Range	T _j , T _{stg}	-55 ~ +150							°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) Measured with $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$.

(3) P.C.B. mounted with 0.2 X 0.2" (5 X 5 mm) copper pad areas.



Fig.1 Forward Current Derating Curve

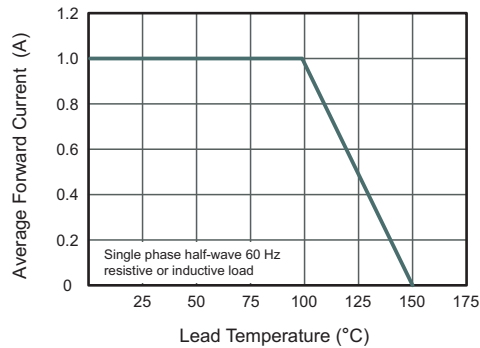


Fig.2 Typical Reverse Characteristics

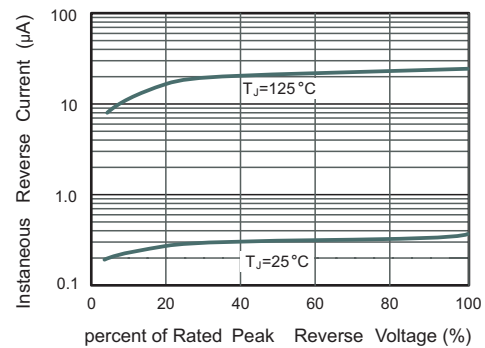


Fig.3 Typical Forward Characteristics

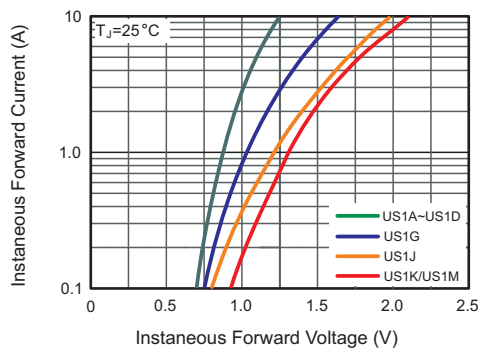


Fig.4 Typical Junction Capacitance

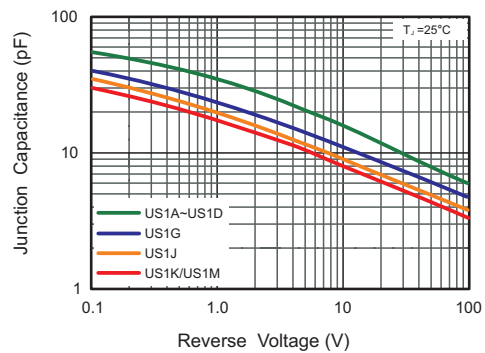
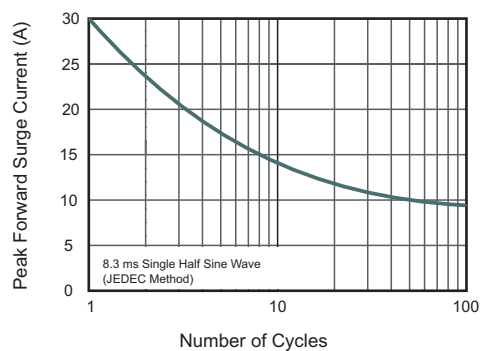


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

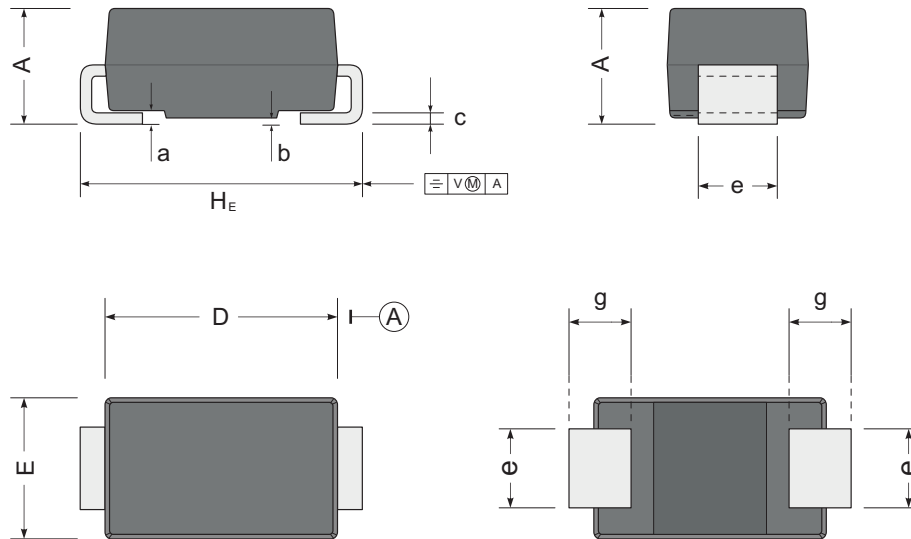




PACKAGE OUTLINE

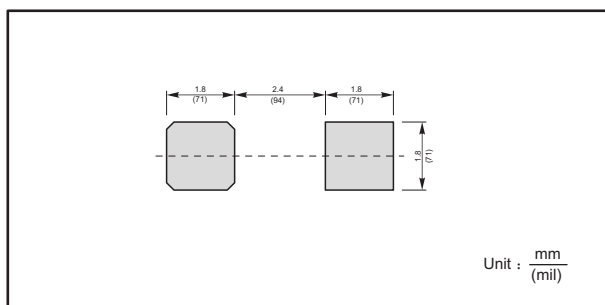
Plastic surface mounted package; 2 leads

SMA



UNIT		A	D	E	H _E	c	e	g	b	a
mm	max	2.2	4.5	2.7	5.2	0.31	1.6	1.5	0.2	0.3
	min	1.9	4.0	2.3	4.7	0.15	1.3	0.9	0.05	
mil	max	87	181	106	205	12	63	59	7.9	12
	min	75	157	91	185	6	51	35	2	

The recommended mounting pad size



Marking

Type number	Marking code
US1A	US1A
US1B	US1B
US1D	US1D
US1G	US1G
US1J	US1J
US1K	US1K
US1M	US1M



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